

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method of manufacturing a semiconductor device comprising:

arranging at least a part of a portion of a lead frame that is to be sealed with a resin, and a portion for use as an outer lead having a removable member thereon, respectively, in a cavity of a metal mold;

filling a sealing resin into the cavity of said metal mold, and hardening the sealing resin;

removing the lead frame sealed with the resin from said metal mold; and

removing a the removable member ~~covering a surface layer region of the section~~, and ~~removing~~ sealing resin over the member, ~~for use as to become the outer lead portion~~, of said lead frame.

2. (Original) The method of manufacturing the semiconductor device according to claim 1, wherein

a plurality of semiconductor device constituent sections are arranged in a common cavity of said metal mold on said lead frame.

3. (Currently Amended) A method of manufacturing a semiconductor device comprising:

fixedly attaching removable members to both sides of a section, for use as an outer lead, of a lead frame;

arranging a section, to be sealed with a resin, of said lead frame including said removable members in a cavity of a metal mold;

filling a sealing resin into the cavity of said metal mold, and hardening the sealing resin;

removing the lead frame sealed with the resin from said metal mold;

forming a groove ranging from a surface of said sealing resin to edges of said removable members; and

removing ~~a member covering~~ the removable members from the outer lead section ~~for use as said outer lead, with the portion of sealing resin over the member in which said groove is formed set as a boundary.~~

4. (Previously Presented) The method of manufacturing the semiconductor device according to claim 3, wherein

bonding sheets having removability with respect to the section for use as said outer lead are employed as said removable members.

5. (Previously Presented) The method of manufacturing the semiconductor device according to claim 3, wherein

spacers detachable from the section for use as said outer lead are employed as said removable members.

6. (Previously Presented) The method of manufacturing the semiconductor device according to claim 3, wherein

spacers each having a removable bonding surface formed between each spacer and the section for use as said outer lead, are employed as said removable members.

7. (Original) The method of manufacturing the semi conductor device according to claim 5, wherein

if said lead frame is arranged in the cavity of said metal mold, said spacers are abutted on inner wall surfaces of the cavity.

8. (Original) The method of manufacturing the semiconductor device according to claim 6, wherein

if said lead frame is arranged in the cavity of said metal mold, said spacers are abutted on inner wall surfaces of the cavity.

9. (Original) The method of manufacturing the semiconductor device according to claim 3, wherein

a plurality of semiconductor device constituent sections are arranged in a common cavity of said metal mold on said lead frame.

10.- 11. (Cancelled)